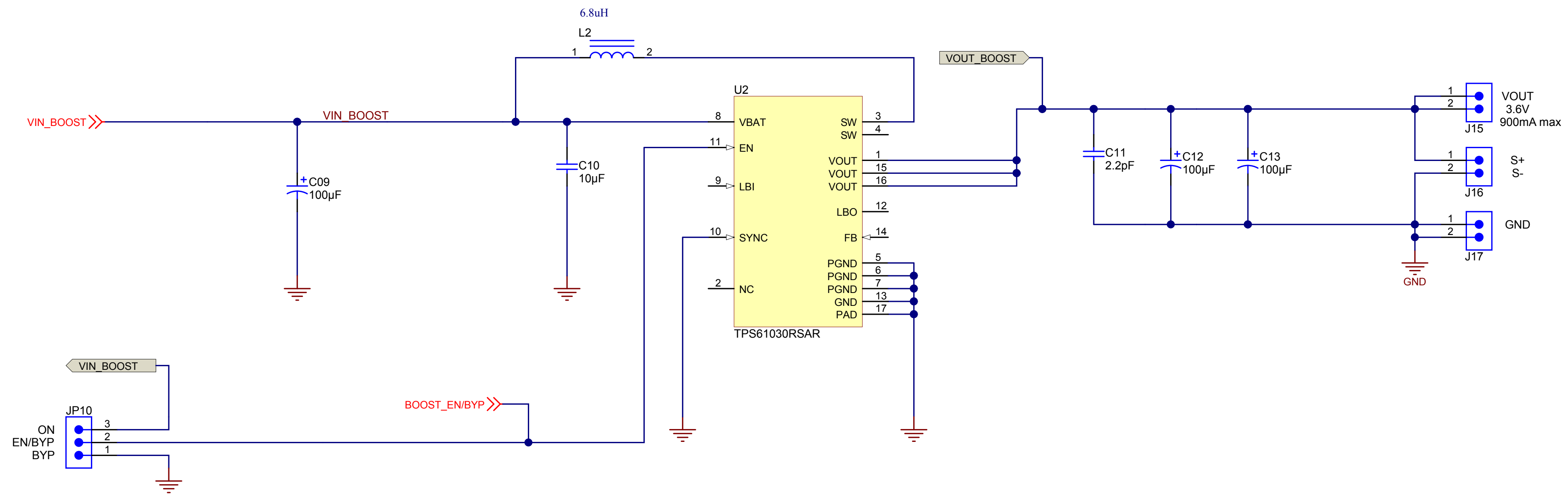



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Number: TIDA-00676	Rev: E1	Designed for: Public Release	Mod. Date: 7/31/2015
SVN Rev: Not in version control	Drawn By:	Project Title: TIDA-00676	Sheet Title:
Engineer: Florian Feckl	File: TIDA-00676_Power_BOOST.SchDoc	Assembly Variant: 001	Sheet: 1 of 1
	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		Size: B

  
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SH-JP1 SH-JP2 SH-JP3 SH-JP4 SH-JP5 SH-JP6 SH-JP7 SH-JP8 SH-JP9 SH-JP10 SH-JP11

FID1  
 H1 H5  
 DNP DNP  
 NY PMS 440 0025 PH 1902C  
 H2 H6  
 DNP DNP  
 NY PMS 440 0025 PH 1902C

PCB Number: TIDA-00676  
 PCB Rev: E1

PCB LOGO  
 Texas Instruments  
 PCB LOGO  
 Pb-Free Symbol  
 PCB LOGO  
 FCC disclaimer

H3 H7  
 DNP DNP  
 NY PMS 440 0025 PH 1902C  
 H4 H8  
 DNP DNP  
 NY PMS 440 0025 PH 1902C  
 FID2 FID3

LBL1  
 DNP  
 Size: 0.65" x 0.20 "

ZZ1  
 Label Assembly Note  
 This Assembly Note is for PCB labels only

ZZ2  
 Assembly Note  
 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
 Assembly Note  
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
 Assembly Note  
 These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

Designed for: <a href="#">Public Release</a>		Mod. Date: 1/22/2015	
Project Title: <a href="#">TIDA-00676</a>			
Sheet Title: <a href="#">Hardware</a>			
Number: <a href="#">TIDA-00676</a>		Rev: <a href="#">E1</a>	
SVN Rev: <a href="#">Not in version control</a>		Assembly Variant: <a href="#">001</a>	
Drawn By:		File: <a href="#">TIDA-00676_Power_Hardware.SchDoc</a>	
Engineer: <a href="#">Florian Feckl</a>		Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	
		Sheet: <a href="#">2</a> of <a href="#">2</a>	
		Size: B	

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